



Features

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Configuration

representative.

Mechanical Data

Case: SO-8

DGD2304

HALF-BRIDGE GATE DRIVER IN SO-8

Floating High-Side Driver in Bootstrap Operation to 600V

290mA Source/600mA Sink Output Current Capability

Schmitt Triggered Logic Inputs with Internal Pull Down

Undervoltage Lockout for High and Low Side Drivers

facilities), please contact us or your local Diodes

https://www.diodes.com/guality/product-definitions/

Case Material: Molded Plastic. "Green" Molding Compound.

Terminals: Finish - Matte Tin Plated Leads, Solderable per

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 3 per J-STD-020

MIL-STD-202, Method 208 (C3) Weight: 0.075 grams (Approximate)

> SO-8 Top View

Extended Temperature Range: -40°C to +125°C

Outputs Tolerant to Negative Transients

Logic Input (HIN and LIN) 3.3V Capability

Drives Two N-channel MOSFETs or IGBTs in a Half Bridge

Internal Logic and Dead Time (100ns) to Protect MOSFETs

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3)

For automotive applications requiring specific change

control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified

Description

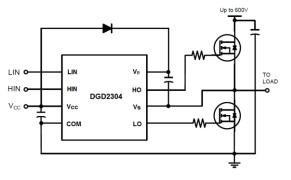
The DGD2304 is a high voltage / high speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2304's high side to switch to 600V in a bootstrap operation.

The DGD2304 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. An internal deadtime of 100ns protects high-voltage MOSFETs from shoot-through.

The DGD2304 is offered in the SO-8 package and operates over an extended -40 $^{\circ}$ C to +125 $^{\circ}$ C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD2304S8-13	DGD2304	13	12	2,500

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and

- Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

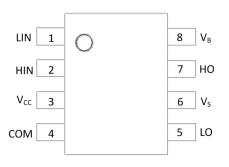


) | | = Manufacturer's Marking DGD2304 = Product Type Marking Code YY = Year (ex: 20 = 2020) WW or WW− = Week (01 to 53)



DGD2304

Pin Diagrams

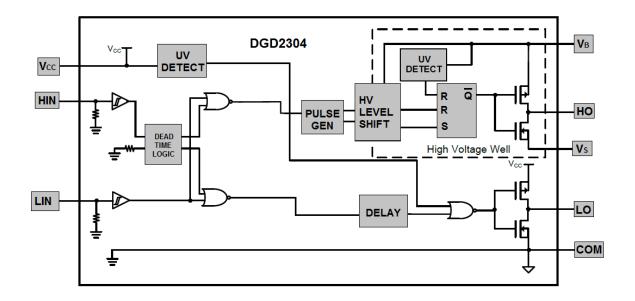




Pin Descriptions

Pin Number	Pin Name	Function
1	LIN	Logic input for Low-Side Gate Driver Output in Phase with LO
2	HIN	Logic Input for High-Side Gate Driver Output in Phase with HO
3	Vcc	Low Side and Logic Fixed Supply
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	Vs	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	Vв	High-Side Floating Supply

Functional Block Diagram





Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
High-Side Floating Supply Voltage	VB	-0.3 to +624	V	
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V	
High-Side Floating Output Voltage	Vно	Vs-0.3 to V _B +0.3	V	
Offset Supply Voltage Transient	dVs/dt	50	V/ns	
Low-Side and Logic Fixed Supply Voltage	V _{CC}	-0.3 to +24	V	
Low-Side Output Voltage	VLO	-0.3 to Vcc+0.3	V	
Logic Input Voltage (HIN and LIN)	Vin	Vss-0.3 to Vcc+0.3	V	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation Linear Derating Factor (Note 5)	PD	1.25	W	
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	55	°C/W	
Operating Temperature	TJ	+150		
Lead Temperature (Soldering, 10s)	TL	+300	°C	
Storage Temperature Range	Tstg	-55 to +150]	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	VB	Vs + 10	Vs + 20	V
High-Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-Side Floating Output Voltage	Vно	Vs	VB	V
Low-Side and Logic Fixed Supply Voltage	Vcc	10	20	V
Low-Side Output Voltage	VLO	0	Vcc	V
Logic Input Voltage	V _{IN}	0	5	V
Ambient Temperature	TA	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to - V_{BS} .



DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	Vih	2.3	—	_	V	Vcc = 10V to 20V
Logic "0" Input Voltage	VIL	_	_	0.7	V	Vcc = 10V to 20V
High Level Output Voltage, VBIAS - VO	Vон	—	0.05	0.2	V	$I_0 = 2mA$
Low Level Output Voltage, Vo	Vol	—	0.02	0.1	V	$I_0 = 2mA$
Offset Supply Leakage Current	I _{LK}	_	_	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V _{BS} Supply Current	IBSQ	20	60	150	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent Vcc Supply Current	lccq	50	260	400	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	_	5.0	40	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	lin-	_	1.0	5.0	μA	$V_{IN} = 0V$
VBS Supply Under-Voltage Positive Going Threshold	VBSUV+	7.7	8.7	9.7	V	—
VBS Supply Under-Voltage Negative Going Threshold	VBSUV-	7.0	8.0	9.0	V	—
Vcc Supply Under-Voltage Positive Going Threshold	Vccuv+	7.7	8.7	9.7	V	_
V _{CC} Supply Under-Voltage Negative Going Threshold	V _{CCUV} -	7.0	8.0	9.0	V	—
Output High Short Circuit Pulsed Current	Io+	60	290	_	mA	Vo = 0V, Pw ≤ 10µs
Output Low Short Circuit Pulsed Current	Io-	130	600	_	mA	$V_0 = 15V, P_W \le 10\mu s$

Note: 7. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the two logic pins: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-On Propagation Delay	ton	_	95	210	ns	Vs = 0V
Turn-Off Propagation Delay	toff	—	100	210	ns	$V_S = 0V \text{ or } 600V$
Delay Matching, HO and LO Turn-On / Turn-Off	t _{DM ON}	_	_	50	ns	—
Turn-On Rise Time	tr	_	70	120	ns	—
Turn-Off Fall Time	tf	_	35	60	ns	—
Deadtime: t _{DT LO-HO} and t _{DT HO-LO}	t _{DT}	80	100	190	ns	—



Timing Waveforms

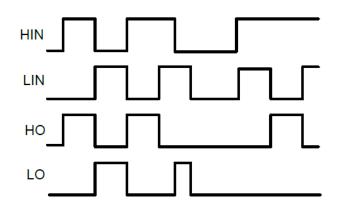


Figure 1. Input / Output Timing Diagram

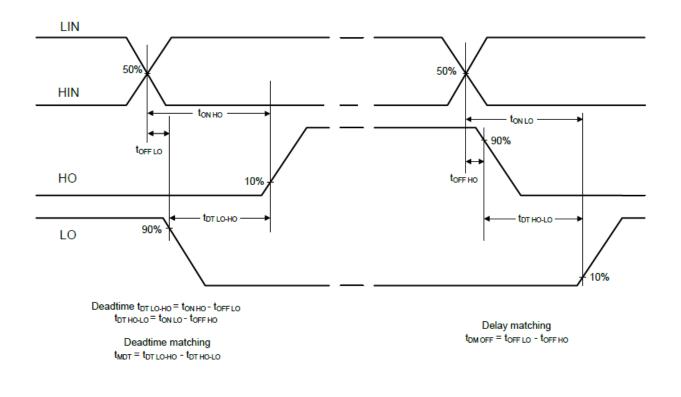


Figure 2. Switching Time Waveform Definition



Typical Performance Characteristics (Vcc = 15V, @TA = +25°C, unless otherwise specified.)

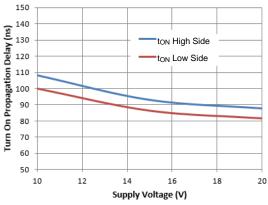


Figure 3. Turn-on Propagation Delay vs. Supply Voltage

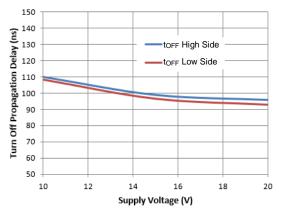


Figure 5. Turn-off Propagation Delay vs. Supply Voltage

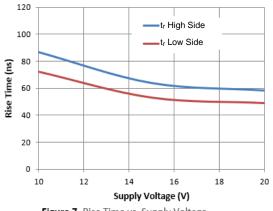


Figure 7. Rise Time vs. Supply Voltage

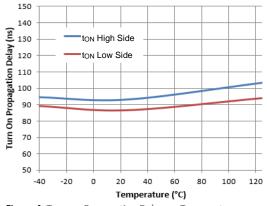


Figure 4. Turn-on Propagation Delay vs. Temperature

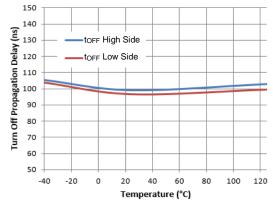
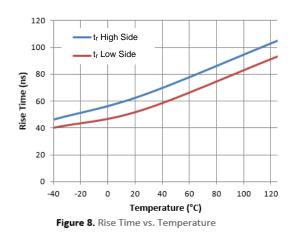
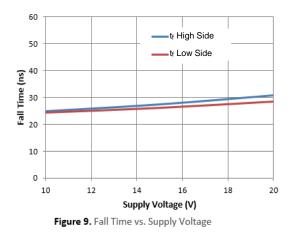


Figure 6. Turn-off Propagation Delay vs. Temperature





Typical Performance Characteristics (continued)



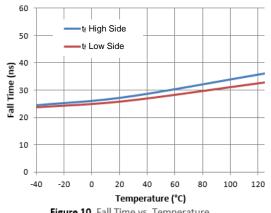
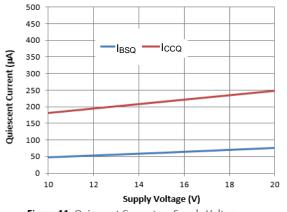


Figure 10. Fall Time vs. Temperature





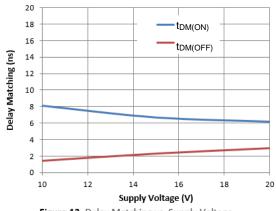
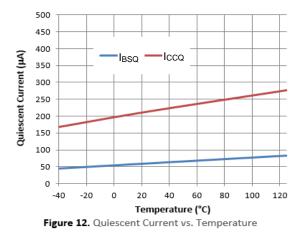


Figure 13. Delay Matching vs. Supply Voltage



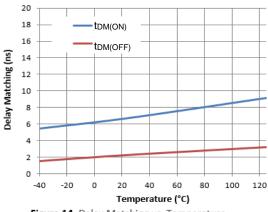


Figure 14. Delay Matching vs. Temperature



Typical Performance Characteristics (continued)

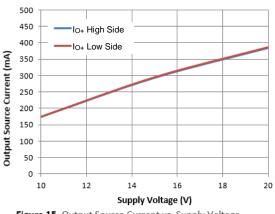


Figure 15. Output Source Current vs. Supply Voltage

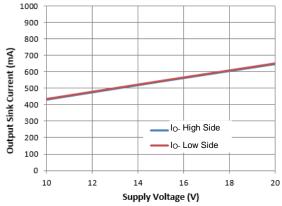


Figure 17. Output Sink Current vs. Supply Voltage

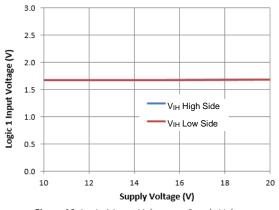
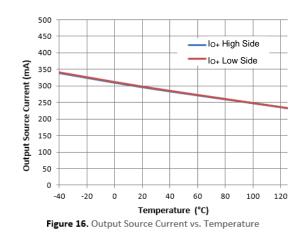
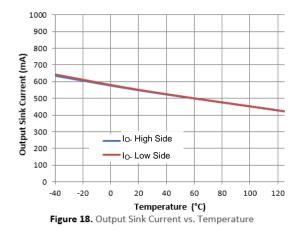


Figure 19. Logic 1 Input Voltage vs. Supply Voltage





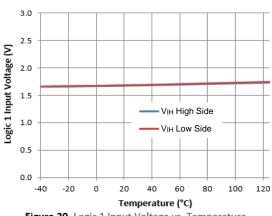
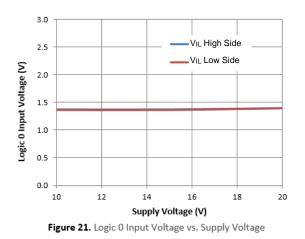


Figure 20. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (continued)



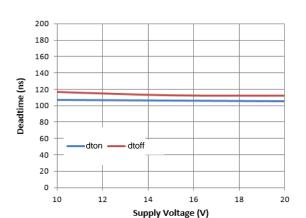


Figure 23. Deadtime vs. Supply Voltage

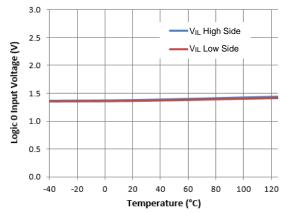


Figure 22. Logic 0 Input Voltage vs. Temperature

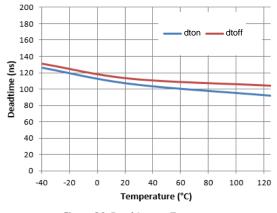


Figure 24. Deadtime vs. Temperature

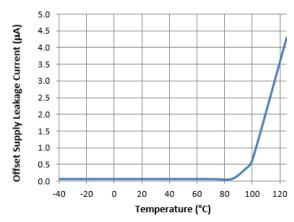
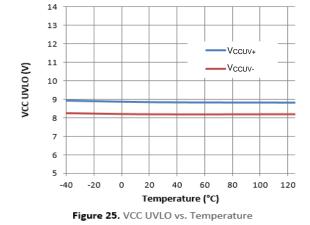


Figure 26. Offset Supply Leakage Current vs. Temperature

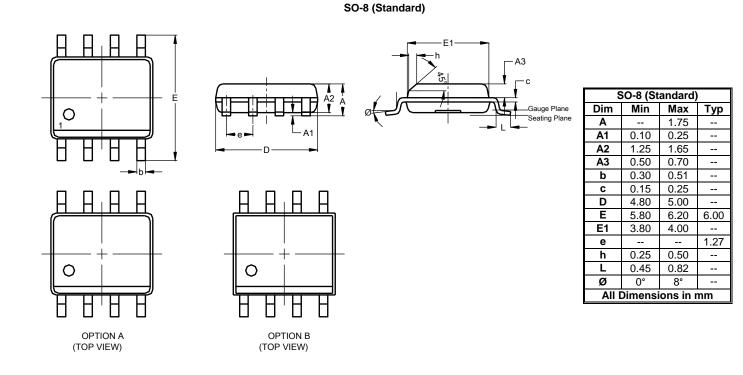


DGD2304 Document number: DS38409 Rev. 6 - 2



Package Outline Dimensions

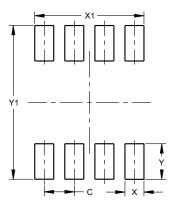
Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Standard)



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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